

## ABSTRACT OF THE DISCLOSURE

An apparatus and method for singulating IC devices or semiconductor devices and/or components thereof. The apparatus includes a flexible membrane or bladder configured to receive an applied fluid pressure on a surface thereof and expand in response to the applied fluid pressure. Upon expansion of the flexible membrane, a semiconductor device or semiconductor device component is contacted by the flexible membrane and immobilized. The semiconductor device may then be subjected to a predetermined test or manufacturing operation. Subsequent any processing to the semiconductor device or component, the fluid pressure is released such that the flexible membrane contracts and releases the semiconductor device to be advanced for further processing, testing, or preparation for shipping.

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